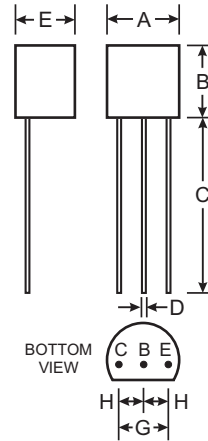


### Features

- Epitaxial Planar Die Construction
- Available in Both Through-Hole and Surface Mount Packages
- Suitable for Switching and Amplifier Applications
- Complementary NPN Types Available (2N3904)

### Mechanical Data

- Case: TO-92, Molded Plastic
- Leads: Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking: Type Number
- Weight: 0.18 grams (approx.)



TO-92		
Dim	Min	Max
A	4.32	4.83
B	4.32	4.78
C	12.50	15.62
D	0.36	0.56
E	3.15	3.94
G	2.29	2.79
H	1.14	1.40
All Dimensions in mm		

### Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	2N3906	Unit
Collector-Base Voltage	$V_{CB0}$	-40	V
Collector-Emitter Voltage	$V_{CE0}$	-40	V
Emitter-Base Voltage	$V_{EB0}$	-5.0	V
Collector Current - Continuous	$I_C$	-100	mA
Collector Current - Peak	$I_{CM}$	-200	mA
Power Dissipation (Note 1)	$P_d$	500	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	250	K/W
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

Notes: 1. Leads maintained at a distance of 2.0mm from body at specified ambient temperature.  
2. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

# Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
DC Current Gain	$h_{FE}$	50 70 100 60 30	— — 300 — —	—	-V <sub>CE</sub> = 1.0V, -I <sub>C</sub> = 0.1mA -V <sub>CE</sub> = 1.0V, -I <sub>C</sub> = 1.0mA -V <sub>CE</sub> = 1.0V, -I <sub>C</sub> = 10mA -V <sub>CE</sub> = 1.0V, -I <sub>C</sub> = 50mA -V <sub>CE</sub> = 1.0V, -I <sub>C</sub> = 100mA
Collector Saturation Voltage	V <sub>CE(SAT)</sub>	—	0.25 0.40	V	(Note 2) -I <sub>C</sub> = 10mA, -I <sub>B</sub> = 1.0mA -I <sub>C</sub> = 50mA, -I <sub>B</sub> = 5.0mA
Base Saturation Voltage	V <sub>BE(SAT)</sub>	—	0.85 0.95	V	(Note 2) -I <sub>C</sub> = 10mA, -I <sub>B</sub> = 1.0mA -I <sub>C</sub> = 50mA, -I <sub>B</sub> = 5.0mA
Collector Cutoff Current	I <sub>CEX</sub>	—	50	nA	-V <sub>EB</sub> = 3.0V, -V <sub>CE</sub> = 30V
Emitter Cutoff Current	I <sub>BL</sub>	—	50	nA	-V <sub>EB</sub> = 3.0V, -V <sub>CE</sub> = 30V
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	40	—	V	-I <sub>C</sub> = 10μA, -I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40	—	V	-I <sub>C</sub> = 1.0mA, -I <sub>B</sub> = 0 (Note 2)
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	5.0	—	V	-I <sub>E</sub> = 10μA, -I <sub>C</sub> = 0
Gain Bandwidth Product	f <sub>T</sub>	250	—	MHz	-V <sub>CE</sub> = 20V, -I <sub>C</sub> = 10mA, f = 100MHz
Collector-Base Capacitance	C <sub>CBO</sub>	—	4.5	pF	-V <sub>CB</sub> = 5.0V, -I <sub>E</sub> = 0, f = 100kHz
Emitter-Base Capacitance	C <sub>EBO</sub>	—	10	pF	-V <sub>EB</sub> = 0.5V, -I <sub>C</sub> = 0, f = 100kHz
Noise Figure	NF	—	5.0	dB	-V <sub>CE</sub> = 5.0V, -I <sub>C</sub> = 100μA, R <sub>G</sub> = 1.0kΩ, f = 10 to 15000Hz
Delay Time	t <sub>d</sub>	—	35	ns	-I <sub>B1</sub> = 1.0mA, -I <sub>C</sub> = 10mA, V <sub>CC</sub> = 3.0V, V <sub>BE(off)</sub> = 0.5V
Rise Time	t <sub>r</sub>	—	35	ns	-I <sub>B1</sub> = 1.0mA, -I <sub>C</sub> = 10mA, -V <sub>CC</sub> = 3.0V, -V <sub>BE(off)</sub> = 0.5V
Storage Time	t <sub>s</sub>	—	225	ns	-I <sub>B1</sub> = -I <sub>B2</sub> = 1.0mA, -I <sub>C</sub> = 10mA, -V <sub>CC</sub> = 3.0V
Fall Time	t <sub>f</sub>	—	75	ns	-I <sub>B1</sub> = -I <sub>B2</sub> = 1.0mA, -I <sub>C</sub> = 10mA, -V <sub>CC</sub> = 3.0V

Notes: 1. Leads maintained at a distance of 2.0mm from body at specified ambient temperature.  
2. Pulse test: Pulse width ≤ 300μs, duty cycle ≤ 2%.

